YIDONG REN

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428 S. Shaw Lane, East Lansing, MI - 48824, USA

RESEARCH INTERESTS

Internet of Things, Wireless Networking (Wireless Local Area Network, Low-Power Wide-Area Network), Ultra-low Power Communication, Sensing

EXPERIENCE

Qualcomm Technologies

Santa Clara, USA

Senior System Engineer, WLAN System Team

2025 - Present

EDUCATION

Michigan State University

East Lansing, USA

Ph.D., Department of Computer Science and Engineering

2021 - 2025

Advisor: Zhichao Cao

University of Electronic Science and Technology of China

Chengdu, China

B.E., Electronic and Information Engineering

2017 - 2021

CONFERENCE PUBLICATIONS

* denotes equal contribution, _ are students I mentor

MobiCom 2025 [C1] LoRaSeek: Boosting Denoising Ability in Neural-enhanced LoRa Decoder via Hierarchical Feature Extraction.

> Khang Nguyen, Yidong Ren, Jialuo Du, Jingkai Lin, Maolin Gan, Shigang Chen, Mi Zhang, Chunyi Peng, Zhichao Cao

The 31st Annual International Conference On Mobile Computing And Networking.

Acceptance ratio: 10.34%

INFOCOM 2025 [C2] AeroEcho: Towards Agricultural Low-power Wide-area Backscatter with Aerial Excitation Source.

Yidong Ren, Gen Li, Yimeng Liu, Younsuk Dong, Zhichao Cao

IEEE Conference on Computer Communications, 2025

Acceptance ratio: 18.66%

SenSys 2025

[C3] Proteus: Enhanced mmWave Leaf Wetness Detection with Cross-Modality Knowledge Trans-

Yimeng Liu, Maolin Gan, Huaili Zeng, Yidong Ren, Gen Li, Jingkai Lin, Younsuk Dong, Xiaobo Tan, Zhichao Cao.

The 23rd ACM Conference on Embedded Networked Sensor Systems.

Acceptance ratio: 18.78%

MobiCom 2024

[C2] SateRIoT: High-performance Ground-Space Networking for Rural IoT.

Yidong Ren, Amalinda Gamage, Li Liu, Mo Li, Shigang Chen, Younsuk Dong, Zhichao Cao.

The 30th Annual International Conference On Mobile Computing And Networking.

Acceptance ratio: 20.85%

MobiCom 2024

[C3] Demeter: Reliable Cross-soil LPWAN with Low-cost Signal Polarization Alignment.

Yidong Ren, Wei Sun, Jialuo Du, Huaili Zeng, Younsuk Dong, Mi Zhang, Shigang Chen, Yunhao

Liu, Tianxing Li, Zhichao Cao.

The 30th Annual International Conference On Mobile Computing And Networking.

Acceptance ratio: 20.85%

MobiCom 2024

[C8] LoRaTrimmer: Optimal Energy Condensation with Chirp Trimming for LoRa Weak Signal Decoding.

Jialuo Du, Yunhao Liu, Yidong Ren, Li Liu, Zhichao Cao.

The 30th Annual International Conference On Mobile Computing And Networking.

Acceptance ratio: 20.85%

MobiSys 2024

[C4] ChirpTransformer: Versatile LoRa Encoding for Low-power Wide-area IoT.

Yidong Ren* (co-primary author), Chenning Li*, Shuai Tong, Shakhrul Iman Siam, Mi Zhang, Jiliang Wang, Yunhao Liu, Zhichao Cao.

The 22nd ACM International Conference on Mobile Systems, Applications, and Services

Acceptance ratio: 16.35%

SenSys 2024

[C9] PiezoBud: A Piezo-Aided Secure Earbud with Practical Speaker Authentication.

Gen Li*, Huaili Zeng*, Hanqing Guo, Yidong Ren, Aiden Dixon, Zhichao Cao and Tianxing Li.

The 22nd ACM Conference on Embedded Networked Sensor Systems.

Acceptance ratio: 18.53%

MobiHoc 2023

[C10] SRLoRa: Neural-enhanced LoRa Weak Signal Decoding with Multi-gateway Super Resolu-

Jialuo Du, Yidong Ren, Zhuizhu, Chenning Li, Zhichao Cao, Qiang Ma, Yunhao Liu.

The 24th International Symposium on Theory, Algorithmic Foundations, and Protocol Design for

Mobile Networks and Mobile Computing

Acceptance ratio: 22.06%

INFOCOM 2023 [C5] Prism: High-throughput LoRa Backscatter with Non-linear Chirps.

Yidong Ren, Puyu Cai, Jinyan Jiang, Jialuo Du, Zhichao Cao.

IEEE Conference on Computer Communications, 2023

Acceptance ratio: 19.21%

ICNP 2022

[C6] Is Lorawan Really Wide? Fine-grained LoRa Link-level Measurement in An Urban Environ-

Yidong Ren* (co-primary author), Li Liu*, Chenning Li*, Zhichao Cao and Shigang Chen.

The 30th IEEE International Conference on Network Protocols.

Acceptance ratio: 21.43%

JOURNAL PUBLICATIONS

TMC

[J1] Morph: ChirpTransformer-based Encoder-decoder Co-design for Reliable LoRa Communication.

Yidong Ren, Maolin Gan, Mi Zhang, Shigang Chen, Zhichao Cao.

Under review of IEEE Transactions on Mobile Computing

TIoT

[J2] NELoRa: Towards Ultra-low SNR LoRa Communication with Neural-enhanced Demodulation. Maolin Gan*, Khang Nguyen*, Jialuo Du, Yidong Ren, Huacheng Zeng, Mi Zhang, Shigang Chen,

Zhichao Cao.

Under review of ACM Transactions on Internet of Things

TMC

[J3] Channel Adapted Antenna Augmentation for Improved Wi-Fi Throughput.

Yanbo Zhang, Weiping Sun, Yidong Ren, Sung-ju Lee, Mo Li.

IEEE Transactions on Mobile Computing, 2022.

BENCKMARK

ICLR ML4IoT

NELoRa-Bench: A Benchmark for Neural-enhanced LoRa Demodulation.

Jialuo Du, Yidong Ren, Mi Zhang, Yunhao Liu and Zhichao Cao.

International Conference on Learning Representations Workshop on Machine Learning for IoT,

2023. Oral

DEMO

MobiCom 2024

Demeter-Demo: Demonstrating Cross-soil LPWAN with Low-cost Signal Polarization Alignment. Yidong Ren, Yawen Wang, Younsuk Dong, Shigang Chen, Mi Zhang, Jiliang Tang, Zhichao Cao.

The 30th Annual International Conference On Mobile Computing And Networking (Demo)

HONOR AND AWARDS

Rising Star, ACM MobiSys	2025
Dissertation Completion Fellowship, Graduate School at Michigan State University	2025
Distinguished Artifact Reviewer, ACM MobiCom	2024
Student Travel Grant, ACM MobiCom	2024
Student Travel Grant, ACM MobiSys	2024
Student Travel Grant, ACM MobiHoc	2023
Student Travel Grant, IEEE ICNP	2022

TEACHING EXPERIENCE Michigan State University, Department of Computer Science and Engineering Teaching Assistant • CSE 220 — Programming in C Spring 2022, Spring 2023, Spring 2024 • CSE 891 — AIoT: Artificial Intelligence in the Edge Fall 2022 **Guest Lecturer** • CSE 891 — AIoT: Artificial Intelligence in the Edge Fall 2023 ACADEMIC SERVICE Programm Committee of • ACM CCS Artifact Evaluation 2025 • USENIX Security Artifact Evaluation 2025 • ACM MobiCom Artifact Evaluation 2024-2025 • ACM MobiSys Artifact Evaluation 2024 • ACM SenSys Artifact Evaluation 2024 • IEEE International Conference on Parallel and Distributed Systems (ICPADS) 2024 Invited Journal Reviewer of • IEEE/ACM Transactions on Networking 2023-2025 • IEEE Transactions on Mobile Computing 2024-2025 · ACM Transactions on Internet of Things 2025 • IEEE Transactions on Communication 2025 • IEEE Transactions on Wireless Communication 2025 • IEEE Internet Computing 2025

2022-2024

2022-2023

02/2022-12/2022

03/2023 - Present

2022

• ACM Transactions on Sensor Network

Now: Honor College, Michigan State University

• IEEE International Symposium on Dynamic Spectrum Access Networks (DySpan)

Now: Master student at Computer Science Department, New York University

Conference Reviewer of

MENTORSHIP

Puyu Cai

EAI MobiQuitous

Khang Nguyen, Nam Nguyen